



**P-Ch 200V Fast Switching MOSFETs**

**Description**

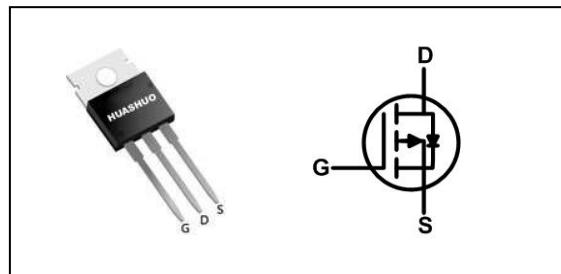
The HSP10P20 uses advanced trench MOSFET technology to provide excellent  $R_{DS(ON)}$  and gate charge for use in a wide variety of other applications.

The HSP10P20 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**Product Summary**

$V_{DS}$	-200	V
$R_{DS(ON),typ}$	650	mΩ
$I_D$	-10	A

**TO-220 Pin Configuration**



- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-200	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-10	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-7.5	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-40	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	81	mJ
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	80	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	1.6	°C/W



**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-200	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_D=-3\text{A}$	---	650	810	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-2	---	-4	V
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-200\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_D=-3\text{A}$	---	5.5	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	5.4	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-50\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_D=-3\text{A}$	---	82	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	19	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	22	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-50\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-3\text{A}$	---	18	---	ns
$T_r$	Rise Time		---	4.5	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	49.5	---	
$T_f$	Fall Time		---	28	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2155	---	pF
$C_{\text{oss}}$	Output Capacitance		---	49	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	39	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-10	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=-3\text{A}$ , $dI/dt=-100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	63	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	195	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



Typical Characteristics

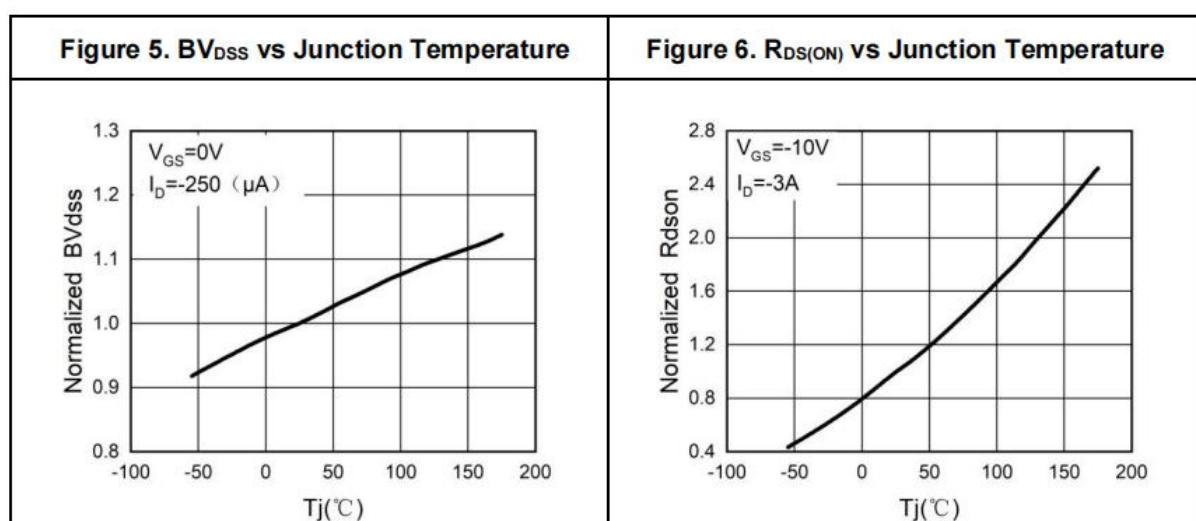
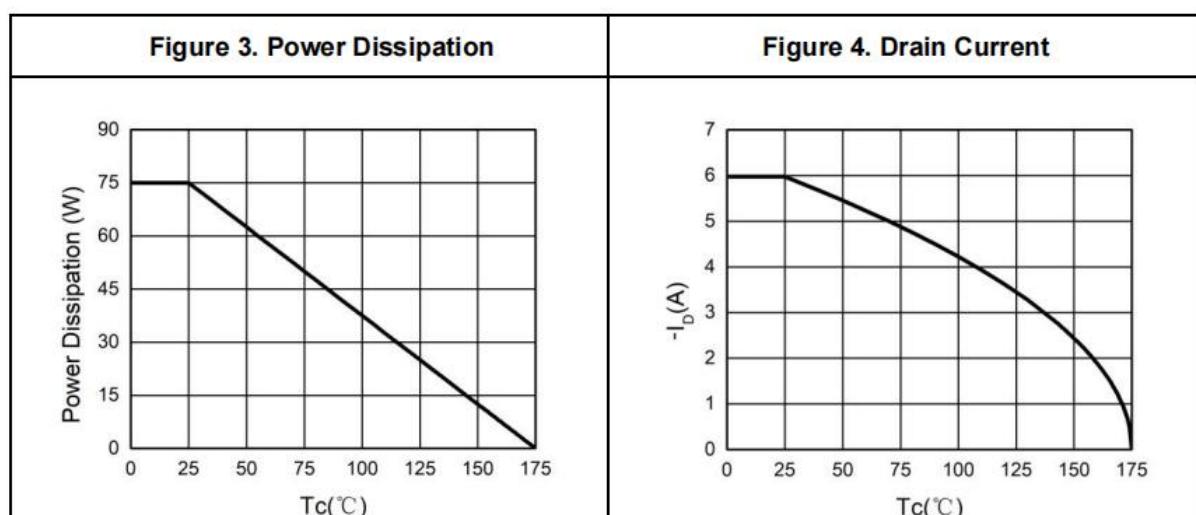
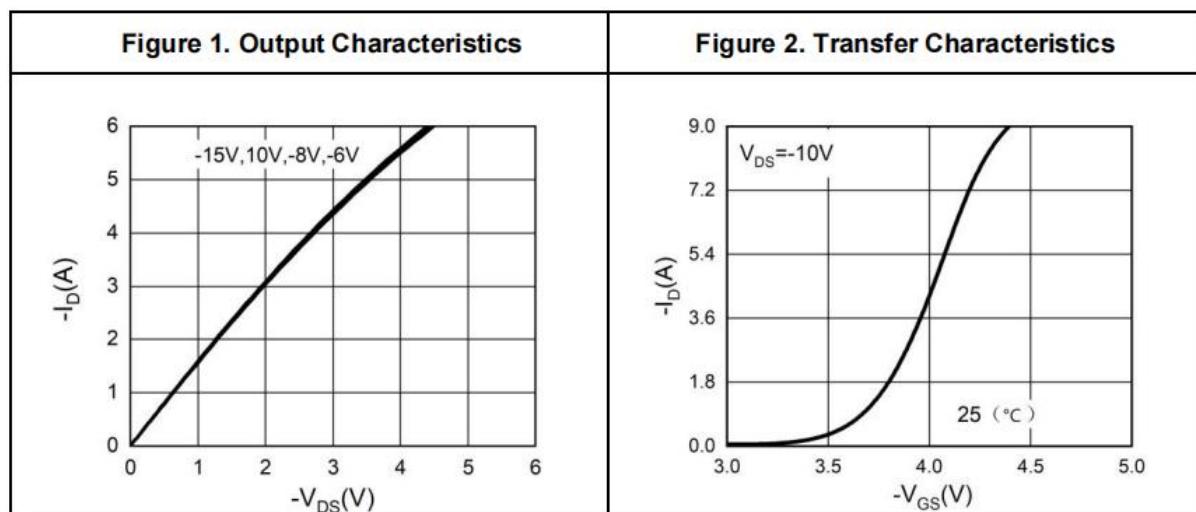




Figure 7. Gate Charge Waveforms

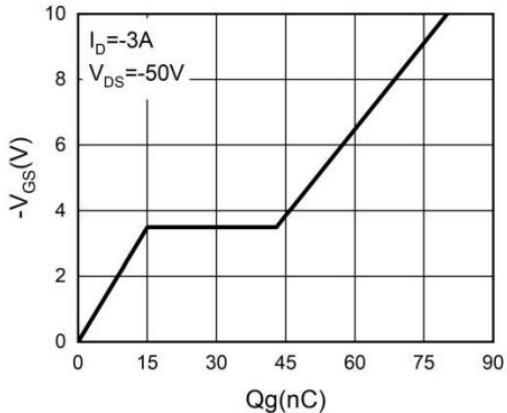


Figure 8. Capacitance

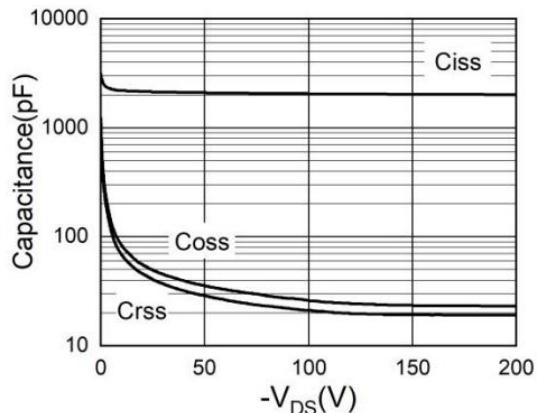


Figure 9. Body-Diode Characteristics

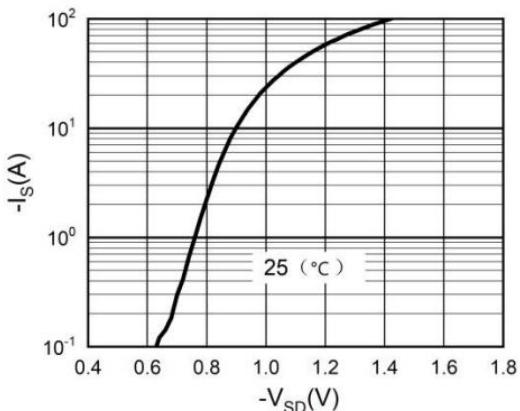
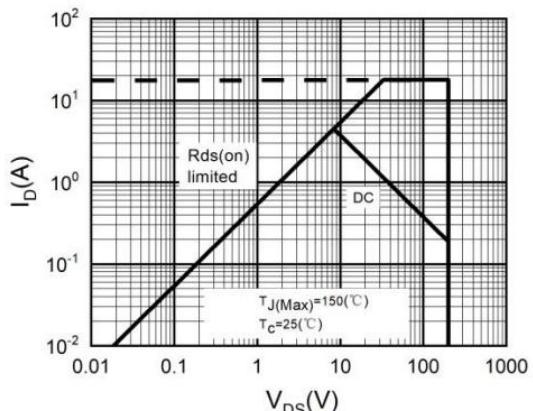
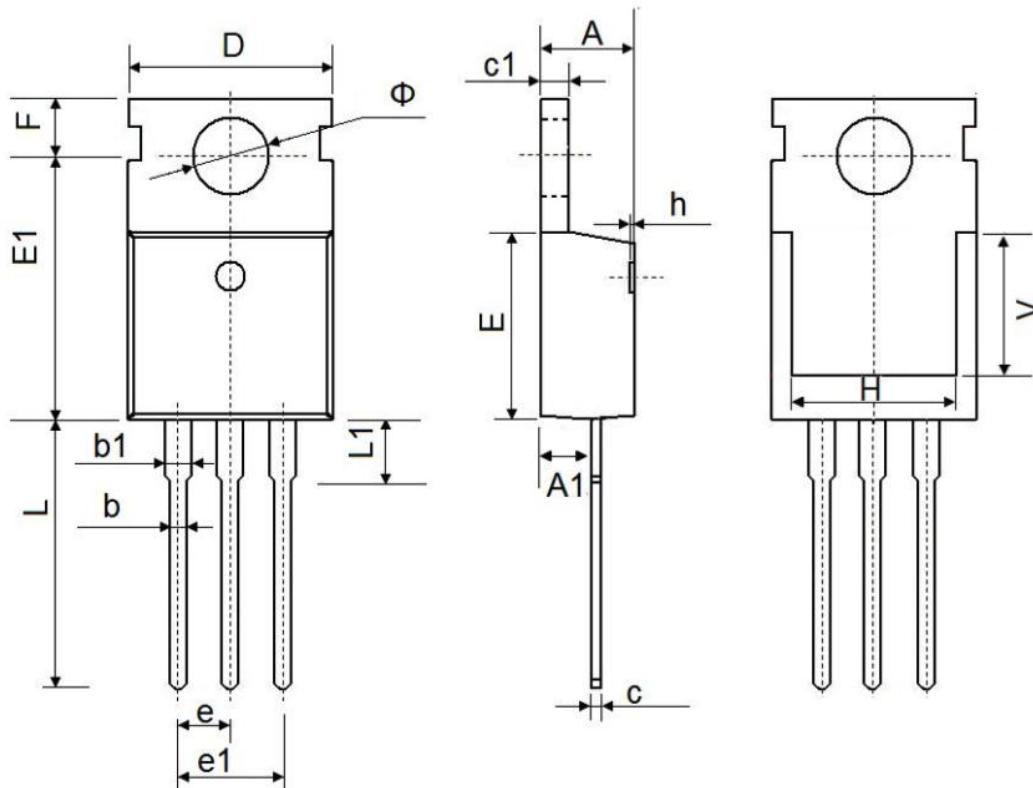


Figure 10. Maximum Safe Operating Area





## TO-220 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max
A	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
c	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500 REF.		0.295 REF.	
Φ	3.400	4.000	0.134	0.157